

MA2S331

Silicon epitaxial planar type

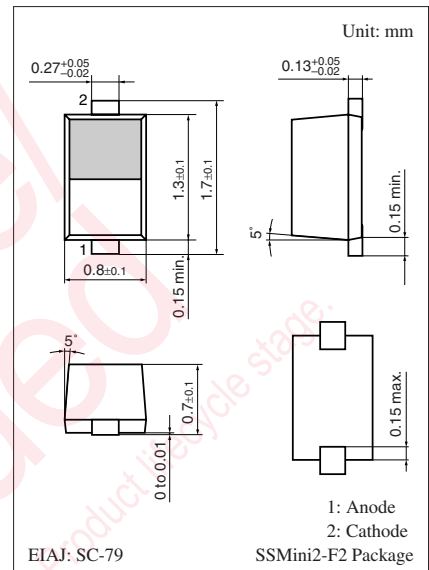
For UHF wireless telegraphic VCO

■ Features

- Small series resistance r_D
- Good linearity of $C - V$ curve
- SS-Mini type package, optimum for downsizing of equipment

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	12	V
Forward current	I_F	20	mA
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$



Marking Symbol: F

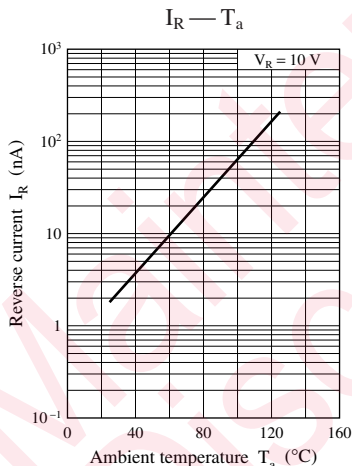
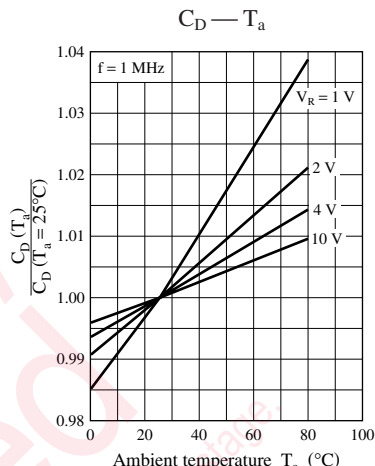
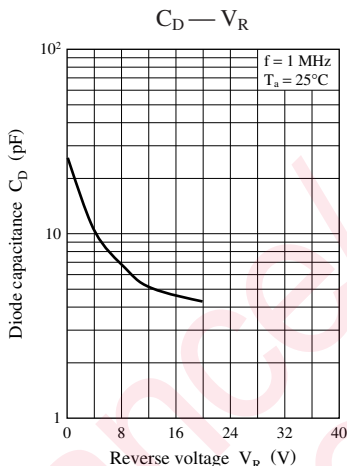
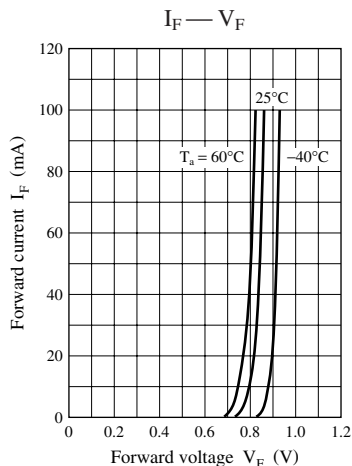
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse current	I_R	$V_R = 12\text{ V}$			10	nA
Diode capacitance	$C_{D(1V)}$	$V_R = 1\text{ V}, f = 1\text{ MHz}$	17.0		20.0	pF
	$C_{D(2V)}$	$V_R = 2\text{ V}, f = 1\text{ MHz}$	14.0	15.0	16.0	
	$C_{D(4V)}$	$V_R = 4\text{ V}, f = 1\text{ MHz}$	10.0		12.4	
	$C_{D(10V)}$	$V_R = 10\text{ V}, f = 1\text{ MHz}$	5.5	6.0	6.5	
Capacitance ratio	$C_{D(1V)}/C_{D(4V)}$		1.53	1.60	1.83	—
	$C_{D(2V)}/C_{D(10V)}$		2.25	2.50	2.75	
Series resistance *	r_D	$C_D = 9\text{ pF}, f = 470\text{ MHz}$		0.18	0.22	Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 470 MHz.

3. *: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER



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